



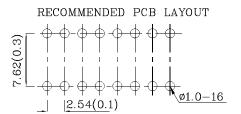
8.89mmx19.05mm LED LIGHT BAR

Features

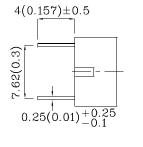
- Robust package
- ullet Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- RoHS compliant

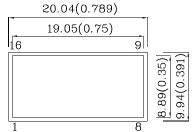


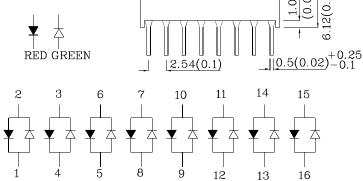




Package Schematics







Notes.

- 1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.
- 2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		UR (GaAsP/ GaP)	MG (GaP)	Unit
Reverse Voltage	$V_{\rm R}$	5	5	V
Forward Current	I_{F}	30	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	160	140	mA
Power Dissipation	P_{D}	75	62.5	mW
Operating Temperature	T_{A}	-40 ~ +85		°C
Storage Temperature	Tstg	-40 ~		
Lead Solder Temperature [2mm Below Package Base]		260°C For 3~5 Seconds		

Operating Characteristics (T _A =25°C)	UR (GaAsP/ GaP)	MG (GaP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2	2.2	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	2.5	V
Reverse Current (Max.) (V _R =5V)	I_{R}	10	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λΡ	627*	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=20\text{mA})$	λD	617*	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)		45	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	15	pF

	Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (IF=20mA) mcd		Wavelength CIE127-2007* nm λP	Description
				min.	typ.		
XI	VEHDM/G999⊭M	Red	GaAsP/GaP	12 5*	29 10*	627*	White Diffused
	XEURMG2889M	XEURMG2885M Green	GaP	12 5*	31 9*	565*	wnite Diffused

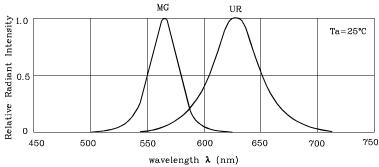
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Mar 12,2014



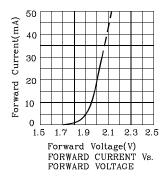


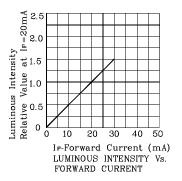


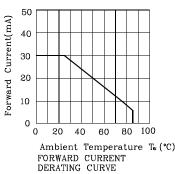


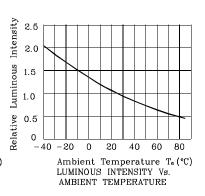
RELATIVE INTENSITY Vs. CIE WAVELENGTH

UR

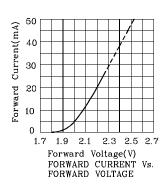


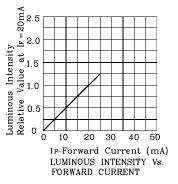


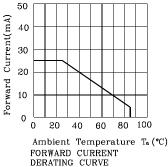


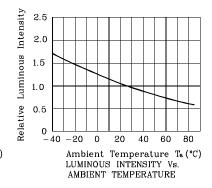


♦ MG

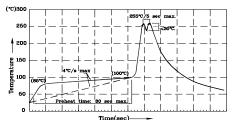








Wave Soldering Profile Thru-Hole Products (Pb-Free Components)



3.Do not apply stress to the epoxy resin while the temperature is a 4. Fixtures should not incur stress on the component when mounting during soldering process.
3.Mc 305 solder alloy is recommended.
3.No more than one wave soldering pass.
7. During wave soldering, the PCB top-surface temperature should be kept below 105°C.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

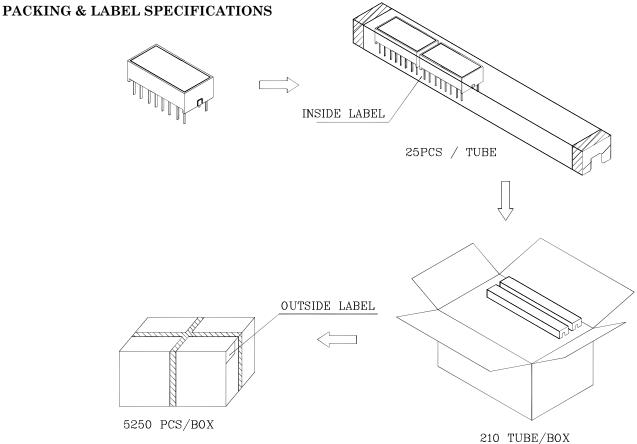
2. Luminous Intensity / Luminous Flux: +/-15%

3. Forward Voltage: +/-0.1V

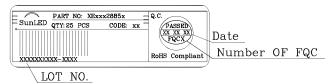
Note: Accuracy may depend on the sorting parameters.



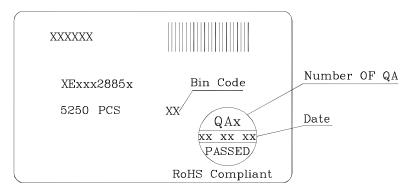
www.SunLEDusa.com



Inside Label On IC-tube



Outside Label On Box



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